ABSOLUTE MAXIMUM RATINGS

Operating Temperature Ranges	
MAX5253_C_P	0°C to +70°C
MAX5253_E_P	40°C to +85°C
MAX5253BMJP	55°C to +125°C
Storage Temperature Range	
Lead Temperature (soldering, 1	0s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = +3.0V \text{ to } +3.6V, \text{AGND} = \text{DGND} = 0V, \text{REFAB} = \text{REFCD} = 1.25V, \text{R}_{L} = 5\text{k}\Omega, \text{C}_{L} = 100\text{pF}, \text{T}_{A} = \text{T}_{MIN} \text{ to T}_{MAX}, \text{ unless otherwise noted.}$ Typical values are at T_A = +25°C. Output buffer connected in unity-gain configuration (Figure 9).)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS			
STATIC PERFORMANCE—ANALOG SECTION									
Resolution	N		12			Bits			
Into and Naulin a suit.		MAX5253AC/E		±0.25	±0.5				
Integral Nonlinearity (Note 1)	INL	MAX5253BC/E			±1.0	LSB			
(14010-1)		MAX5253BMJP			±2.0				
Differential Nonlinearity	DNL	Guaranteed monotonic			±1.0	LSB			
Offset Error	Vos				±6.0	mV			
Offset-Error Tempco				6		ppm/°C			
Gain Error	GE	(Note 1)			±4.0	LSB			
Gain-Error Tempco				1		ppm/°C			
Power-Supply Rejection Ratio	PSRR	$V_{DD} = +3.0V \text{ to } +3.6V$			300	μV/V			
MATCHING PERFORMANCE ($T_A = +25^{\circ}C$								
Gain Error	GE				±4.0	LSB			
Offset Error				±1.0	±6.0	mV			
Integral Nonlinearity	INL			±0.35	±1.0	LSB			
REFERENCE INPUT	•								
Reference Input Range	VREF		0	V	'DD - 1.4	V			
Reference Input Resistance	R _{REF}	Code-dependent, minimum at code 555 hex	8			kΩ			

2 ______ *NIXI/*M

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = +3.0V \text{ to } +3.6V, \text{AGND} = \text{DGND} = 0V, \text{REFAB} = \text{REFCD} = 1.25V, \text{R}_{L} = 5k\Omega, \text{C}_{L} = 100p\text{F}, \text{T}_{A} = \text{T}_{MIN} \text{ to T}_{MAX}, \text{ unless otherwise noted. Typical values are at T}_{A} = +25^{\circ}\text{C}$. Output buffer connected in unity-gain configuration (Figure 9).)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
MULTIPLYING-MODE PERFORMANCE								
Reference -3dB Bandwidth		V _{REF} = 0.67V _{P-P}		650		kHz		
Reference Feedthrough		Input code = all 0s, V _{REF} = 1.6V _{P-P} at 1kHz		-84		dB		
Signal-to-Noise Plus Distortion Ratio	SINAD	V _{REF} = 1V _{P-P} at 25kHz		72		dB		
DIGITAL INPUTS								
Input High Voltage	VIH		2.0			V		
Input Low Voltage	V _{IL}				0.8	V		
Input Leakage Current	I _{IN}	V _{IN} = 0V or V _{DD}		0.01	±0.1	μΑ		
Input Capacitance	CIN			8		рF		
DIGITAL OUTPUTS								
Output High Voltage	VoH	ISOURCE = 2mA	V _{DD} - 0.5			V		
Output Low Voltage	Vol	ISINK = 2mA		0.13	0.4	V		
DYNAMIC PERFORMANCE								
Voltage Output Slew Rate	SR			0.6		V/µs		
Output Settling Time		To ±1/2LSB, VSTEP = 1.25V		16		μs		
Output Voltage Swing		Rail-to-Rail® (Note 2)	(to V _{DD}		V		
Current into FB_				0	0.1	μΑ		
OUT_ Leakage Current in Shutdown		R _L = ∞		0.01	±1	μΑ		
Start-Up Time Exiting Shutdown Mode				20		μs		
Digital Feedthrough		$\overline{\text{CS}} = \text{V}_{\text{DD}}, \text{DIN} = 100 \text{kHz}$		5		nV-s		
Digital Crosstalk				5		nV-s		
POWER SUPPLIES								
Supply Voltage	V _{DD}	(Note 3)	3.0		3.6	V		
Supply Current	IDD	(Note 4)		0.82	0.98	mA		
Supply Current in Shutdown		(Note 4)		3	20	μΑ		
Reference Current in Shutdown				0.01	±1	μΑ		

Note 1: Guaranteed from code 11 to code 4095 in unity-gain configuration.

Note 2: Accuracy is better than 0.5LSB for Vout = 6mV to Vpp - 80mV, guaranteed by PSR test on endpoints.

Note 3: Remains operational with supply voltage as low as +2.7V.

Note 4: $R_L = \infty$, digital inputs at DGND or V_{DD} .

Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.



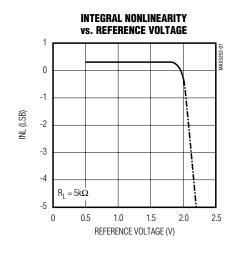
TIMING CHARACTERISTICS

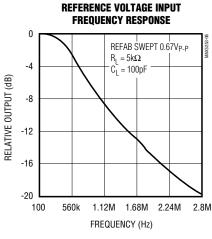
 $(V_{DD} = +3.0V \text{ to } +3.6V, \text{ AGND} = \text{DGND} = 0V, \text{ REFAB} = \text{REFCD} = 1.25V, \text{ R}_{L} = 5\text{k}\Omega, \text{ C}_{L} = 100\text{pF}, \text{ T}_{A} = \text{T}_{MIN} \text{ to T}_{MAX}, \text{ unless otherwise noted. Typical values are at T}_{A} = +25^{\circ}\text{C}$. Output buffer connected in unity-gain configuration (Figure 9).)

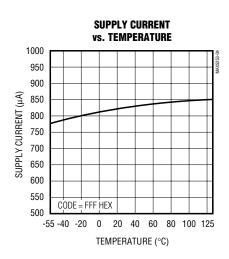
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Clock Period	tcp		100			ns
SCLK Pulse Width High	tch		40			ns
SCLK Pulse Width Low	tcL		40			ns
CS Fall to SCLK Rise Setup Time	tcss		40			ns
SCLK Rise to CS Rise Hold Time	tcsh		0			ns
DIN Setup Time	tDS		40			ns
DIN Hold Time	tDH		0			ns
SCLK Rise to DOUT Valid Propagation Delay	t _{D01}	C _L = 200pF			120	ns
SCLK Fall to DOUT Valid Propagation Delay	t _{D02}	C _L = 200pF			120	ns
SCLK Rise to CS Fall Delay	tcso		40			ns
CS Rise to SCLK Rise Hold Time	tcs1		40			ns
CS Pulse Width High	tcsw		100			ns

Typical Operating Characteristics

 $(V_{DD} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$

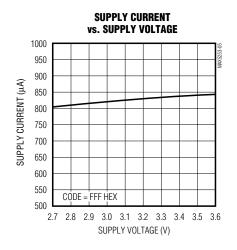


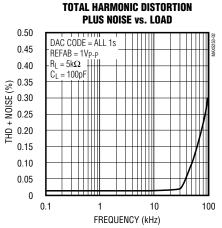


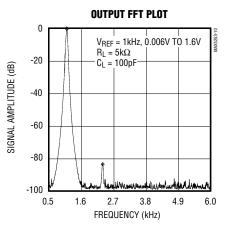


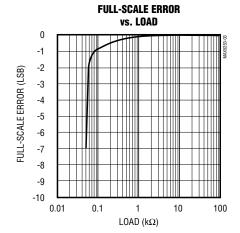
Typical Operating Characteristics (continued)

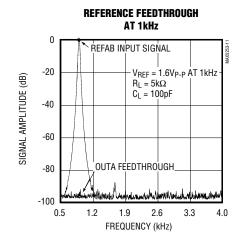
 $(V_{DD} = +3.3V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$









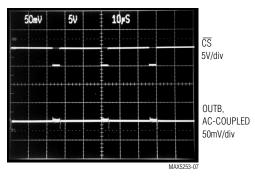


MIXIM

Typical Operating Characteristics (continued)

(V_{DD} = +3.3V, T_A = +25°C, unless otherwise noted.)

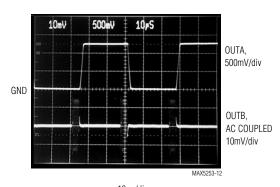
MAJOR-CARRY TRANSITION



10µs/div

 $V_{REF}=1.25V,\,R_L=5k\Omega,\,C_L=100pF$

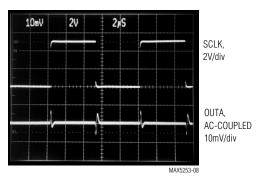
ANALOG CROSSTALK



10µs/div

 $V_{REF}=1.25V,\,R_L=5k\Omega,\,C_L=100pF$ DAC A CODE SWITCHING FROM 00B HEX TO FFF HEX DAC B CODE SET TO 800 HEX

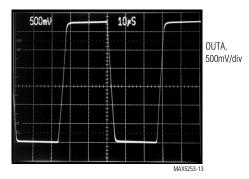
DIGITAL FEEDTHROUGH (SCLK = 100kHz)



2μs/div

$$\begin{split} &V_{REF}=1.25\text{V},\,R_L=5\text{k}\Omega,\,C_L=100\text{pF}\\ &\overline{CS}=\overline{PDL}=\overline{CL}=3.3\text{V},\,\text{DIN}=0\text{V}\\ &\text{DAC A CODE SET TO 800 HEX} \end{split}$$

DYNAMIC RESPONSE



10µs/div

 $V_{REF}=1.25V,\,R_L=5k\Omega,\,C_L=100pF$ SWITCHING FROM CODE 000 HEX TO FB4 HEX OUTPUT AMPLIFIER GAIN = +2.6

Pin Description

PIN	NAME	FUNCTION
1	AGND	Analog Ground
2	FBA	DAC A Output Amplifier Feedback
3	OUTA	DAC A Output Voltage
4	OUTB	DAC B Output Voltage
5	FBB	DAC B Output Amplifier Feedback
6	REFAB	Reference Voltage Input for DAC A and DAC B
7	CL	Clears All DACs and Registers. Resets all outputs (OUT_, UPO, DOUT) to 0, active low.
8	CS	Chip-Select Input. Active low.
9	DIN	Serial-Data Input
10	SCLK	Serial Clock Input
11	DGND	Digital Ground
12	DOUT	Serial-Data Output
13	UPO	User-Programmable Logic Output
14	PDL	Power-Down Lockout. Active low. Locks out software shutdown if low.
15	REFCD	Reference Voltage Input for DAC C and DAC D
16	FBC	DAC C Output Amplifier Feedback
17	OUTC	DAC C Output Voltage
18	OUTD	DAC D Output Voltage
19	FBD	DAC D Output Amplifier Feedback
20	V _{DD}	Positive Power Supply



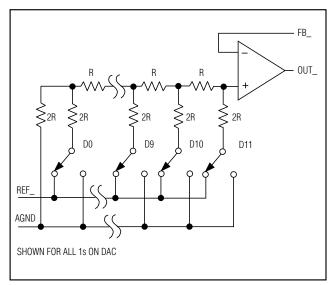


Figure 1. Simplified DAC Circuit Diagram

Detailed Description

The MAX5253 contains four 12-bit, voltage-output digital-to-analog converters (DACs) that are easily addressed using a simple 3-wire serial interface. It includes a 16-bit data-in/data-out shift register, and each DAC has a doubled-buffered input composed of an input register and a DAC register (see *Functional Diagram*). In addition to the four voltage outputs, each amplifier's negative input is available to the user.

The DACs are inverted R-2R ladder networks that convert 12-bit digital inputs into equivalent analog output voltages in proportion to the applied reference voltage inputs. DACs A and B share the REFAB reference input, while DACs C and D share the REFCD reference input. The two reference inputs allow different full-scale output voltage ranges for each pair of DACs. Figure 1 shows a simplified circuit diagram of one of the four DACs.

Reference Inputs

The two reference inputs accept positive DC and AC signals. The voltage at each reference input sets the full-scale output voltage for its two corresponding DACs. The reference input voltage range is 0V to (VDD - 1.4V). The output voltages (VOUT_) are represented by a digitally programmable voltage source as:

$$VOUT = (VREF \times NB / 4096) \times Gain$$

where NB is the numeric value of the DAC's binary input code (0 to 4095), VREF is the reference voltage, and Gain is the externally set voltage gain.

The impedance at each reference input is code-dependent, ranging from a low value of $10k\Omega$ when both DACs connected to the reference have an input code of 555 hex, to a high value exceeding several gigohms (leakage current) with an input code of 000 hex. Because the input impedance at the reference pins is codedependent, load regulation of the reference source is important.

The REFAB and REFCD reference inputs have a $10 k\Omega$ guaranteed minimum input impedance. When the two reference inputs are driven from the same source, the effective minimum impedance is $5 k\Omega$. Driving the REFAB and REFCD pins separately improves reference accuracy.

In shutdown mode, the MAX5253's REFAB and REFCD inputs enter a high-impedance state with a typical input leakage current of 0.01µA.

The reference input capacitance is also code dependent and typically ranges from 20pF with an input code of all 0s to 100pF with an input code of all 1s.

Output Amplifiers

All MAX5253 DAC outputs are internally buffered by precision amplifiers with a typical slew rate of 0.6V/µs. Access to the inverting input of each output amplifier provides the user greater flexibility in output gain setting/signal conditioning (see the *Applications Information* section).

With a full-scale transition at the MAX5253 output, the typical settling time to $\pm 1/2 LSB$ is 16µs when loaded with 5k Ω in parallel with 100pF (loads less than 2k Ω degrade performance).

The MAX5253 output amplifier's output dynamic responses and settling performances are shown in the *Typical Operating Characteristics*.

Shutdown Mode

The MAX5253 features a software-programmable shutdown that reduces supply current to a typical value of 3µA. The power-down lockout (PDL) pin must be high to enable the shutdown mode. Writing 1100XXXXXXXXXXX as the input-control word puts the MAX5253 in shutdown mode (Table 1).

_______NIXI/N

In shutdown mode, the MAX5253 output amplifiers and the reference inputs enter a high-impedance state. The serial interface remains active. Data in the input registers is retained in shutdown, allowing the MAX5253 to recall the output states prior to entering shutdown. Exit shutdown mode by either recalling the previous configuration or by updating the DACs with new data. When powering up the device or bringing it out of shutdown, allow 20µs for the outputs to stabilize.

Serial-Interface Configurations

The MAX5253's 3-wire serial interface is compatible with both MICROWIRE (Figure 2) and SPI/QSPI (Figure 3). The serial input word consists of two address bits and two control bits followed by 12 data bits (MSB first), as shown in Figure 4. The 4-bit address/ control code determines the MAX5253's response outlined in Table 1. The connection between DOUT and the serial-interface port is not necessary, but may be used for data echo. Data held in the MAX5253's shift register can be shifted out of DOUT and returned to the microprocessor (μ P) for data verification.

The MAX5253's digital inputs are double buffered. Depending on the command issued through the serial interface, the input register(s) can be loaded without affecting the DAC register(s), the DAC register(s) can be loaded directly, or all four DAC registers can be updated simultaneously from the input registers (Table 1).

Serial-Interface Description

The MAX5253 requires 16 bits of serial data. Table 1 lists the serial-interface programming commands. For certain commands, the 12 data bits are "don't cares." Data is sent MSB first and can be sent in two 8-bit packets or one 16-bit word (CS must remain low until 16 bits are transferred). The serial data is composed of two DAC address bits (A1, A0) and two control bits (C1,C0), followed by the 12 data bits D11...D0 (Figure 4). The 4-bit address/control code determines:

- The register(s) to be updated
- The clock edge on which data is to be clocked out through the serial-data output (DOUT)
- The state of the user-programmable logic output (UPO)
- If the part is to go into shutdown mode (assuming PDL is high)
- How the part is configured when exiting shutdown mode

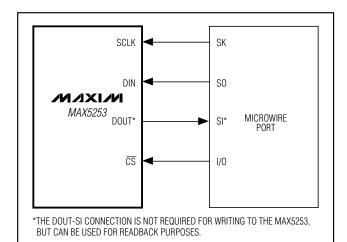


Figure 2. Connections for MICROWIRE

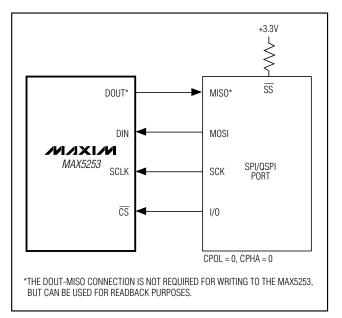


Figure 3. Connections for SPI/QSPI

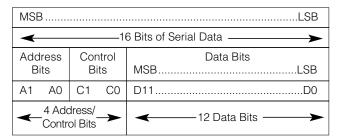


Figure 4. Serial-Data Format



Table 1. Serial-Interface Programming Commands

16-BIT SERIAL WORD			ERIAL W	ORD	
A 1	Α0	C1	C0	D11D0 MSB LSB	FUNCTION
0	0	0	1	12-bit DAC data	Load input register A; DAC registers unchanged.
0	1	0	1	12-bit DAC data	Load input register B; DAC registers unchanged.
1	0	0	1	12-bit DAC data	Load input register C; DAC registers unchanged.
1	1	0	1	12-bit DAC data	Load input register D; DAC registers unchanged.
0	0	1	1	12-bit DAC data	Load input register A; all DAC registers updated.
0	1	1	1	12-bit DAC data	Load input register B; all DAC registers updated.
1	0	1	1	12-bit DAC data	Load input register C; all DAC registers updated.
1	1	1	1	12-bit DAC data	Load input register D; all DAC registers updated.
0	1	0	0	XXXXXXXXXX	Update all DAC registers from their respective input registers (exit shutdown mode).
1	0	0	0	12-bit DAC data	Load all DAC registers from shift register (exit shutdown mode).
1	1	0	0	XXXXXXXXXXX	Enter shutdown mode (provided PDL = 1)
0	0	1	0	XXXXXXXXXXX	UPO goes low (default)
0	1	1	0	XXXXXXXXXXX	UPO goes high
0	0	0	0	XXXXXXXXXXX	No operation (NOP) to DAC registers
1	1	1	0	XXXXXXXXXX	Mode 1, DOUT clocked out on SCLK's rising edge. All DAC registers updated.
1	0	1	0	xxxxxxxxxx	Mode 0, DOUT clocked out on SCLK's falling edge. All DAC registers updated (default).

[&]quot;X" = Don't care

Figure 5 shows the serial-interface timing requirements. The chip-select pin (\overline{CS}) must be low to enable the DAC's serial interface. When \overline{CS} is high, the interface control circuitry is disabled. \overline{CS} must go low at least tCSS before the rising serial clock (SCLK) edge to properly clock in the first bit. When \overline{CS} is low, data is clocked into the internal shift register through the serial-data input pin (DIN) on SCLK's rising edge. The maximum guaranteed clock frequency is 10MHz. Data is latched into the appropriate MAX5253 input/DAC registers on \overline{CS} 's rising edge.

The programming command Load-All-DACs-From-Shift-Register allows all input and DAC registers to be simultaneously loaded with the same digital code from the input shift register. The no operation (NOP) command leaves the register contents unaffected and is useful when the MAX5253 is configured in a daisy chain (see the *Daisy Chaining Devices* section). The command to

change the clock edge on which serial data is shifted out of DOUT also loads data from all input registers to their respective DAC registers.

Serial-Data Output (DOUT)

The serial-data output, DOUT, is the internal shift register's output. The MAX5253 can be programmed so that data is clocked out of DOUT on SCLK's rising edge (Mode 1) or falling edge (Mode 0). In Mode 0, output data at DOUT lags input data at DIN by 16.5 clock cycles, maintaining compatibility with Microwire, SPI/QSPI, and other serial interfaces. In Mode 1, output data lags input data by 16 clock cycles. On power-up, DOUT defaults to Mode 0 timing.

User-Programmable Logic Output (UPO)

The user-programmable logic output, UPO, allows an external device to be controlled through the MAX5253 serial interface (Table 1).

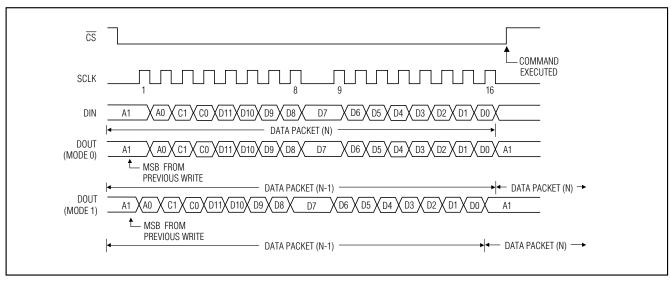


Figure 5. Serial-Interface Timing Diagram

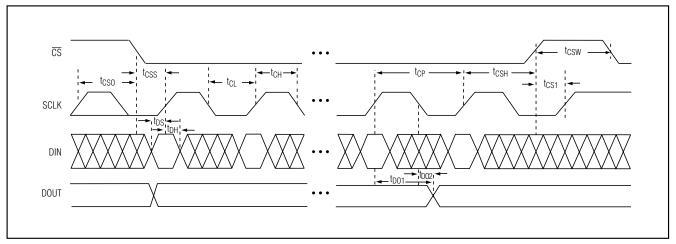


Figure 6. Detailed Serial-Interface Timing Diagram

Power-Down Lockout (PDL)

The power-down lockout pin PDL disables software shutdown when low. When in shutdown, transitioning PDL from high to low wakes up the part with the output set to the state prior to shutdown. PDL could also be used to asynchronously wake up the device.

Daisy-Chaining Devices

Any number of MAX5253s can be daisy chained by connecting the DOUT pin of one device to the DIN pin of the following device in the chain (Figure 7).

Since the MAX5253's DOUT pin has an internal active pull-up, the DOUT sink/source capability determines the time required to discharge/charge a capacitive load. Refer to the serial-data-out VOH and VOL specifications in the *Electrical Characteristics*.

Figure 8 shows an alternate method of connecting several MAX5253s. In this configuration, the data bus is common to all devices; data is not shifted through a daisy chain. More I/O lines are required in this configuration because a dedicated chip-select input $\overline{(CS)}$ is required for each IC.



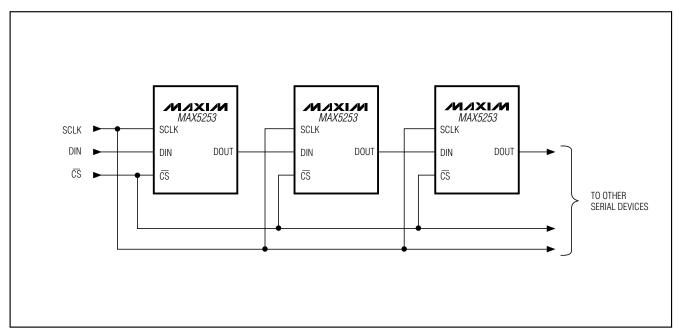


Figure 7. Daisy-Chaining MAX5253s

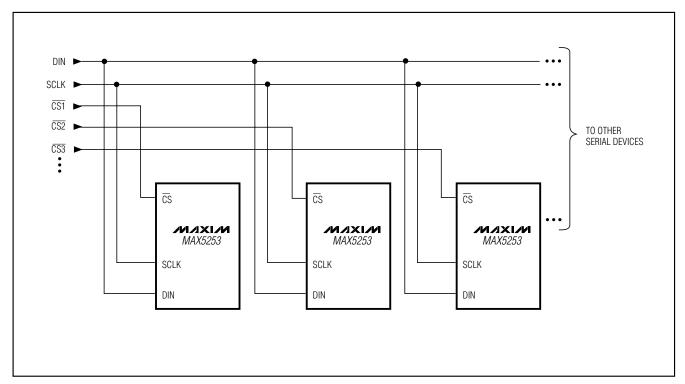


Figure 8. Multiple MAX5253s Sharing a Common DIN Line

12 ______ **//**| **//**| **//**|

Applications Information

Unipolar Output

For a unipolar output, the output voltages and the reference inputs have the same polarity. Figure 9 shows the MAX5253 unipolar output circuit, which is also the typical operating circuit. Table 2 lists the unipolar output codes.

For rail-to-rail outputs, see Figure 10. This circuit shows the MAX5253 with the output amplifiers configured with a closed-loop gain of +2.6 to provide 0V to 3.25V full-scale range when a 1.25V reference is used.

Table 2. Unipolar Code Table

DAC MSB	CONTEN	ITS LSB	ANALOG OUTPUT
1111	1111	1111	+V _{REF} (4095 / 4096)
1000	0000	0001	+V _{REF} (2049 / 4096)
1000	0000	0000	$+V_{REF}\left(\frac{2048}{4096}\right) = \frac{+V_{REF}}{2}$
0111	1111	1111	+V _{REF} (<u>2047</u>)
0000	0000	0001	+V _{REF} (1/4096)
0000	0000	0000	OV

Table 3. Bipolar Code Table

DAC MSB	CONTEN	ITS LSB	ANALOG OUTPUT
1111	1111	1111	+V _{REF} (<u>2047</u>)
1000	0000	0001	+V _{REF} (1/2048)
1000	0000	0000	OV
0111	1111	1111	$-V_{REF} \left(\frac{1}{2048} \right)$
0000	0000	0001	-V _{REF} (2047)
0000	0000	0000	$-V_{REF} \left(\frac{2048}{2048} \right) = -V_{REF}$

Bipolar Output

The MAX5253 outputs can be configured for bipolar operation using Figure 11's circuit.

where NB is the numeric value of the DAC's binary input code. Table 3 shows digital codes (offset binary) and corresponding output voltages for Figure 11's circuit

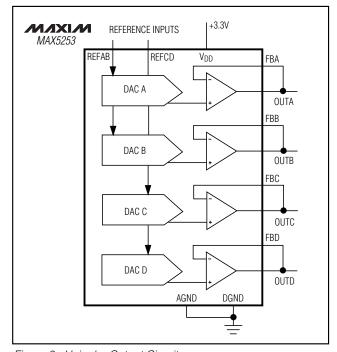


Figure 9. Unipolar Output Circuit

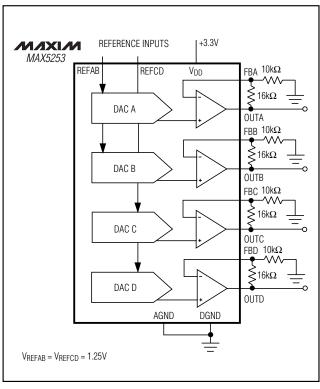


Figure 10. Unipolar Rail-to-Rail Output Circuit

REF_ DAC FB OUT OUT MAX5253 $R1 = R2 = 10k\Omega \pm 0.1\%$

Figure 11. Bipolar Output Circuit

Using an AC Reference

In applications where the reference has AC signal components, the MAX5253 has multiplying capability within the reference input range specifications. Figure 12 shows a technique for applying a sine-wave signal to the reference input where the AC signal is offset before being applied to REFAB/REFCD. The reference voltage must never be more negative than DGND.

The MAX5253's total harmonic distortion plus noise (THD + N) is typically less than -72dB, given a 1V signal swing and input frequencies up to 25kHz. The typical -3dB frequency is 650kHz, as shown in the *Typical Operating Characteristics* graphs.

Digitally Programmable Current Source

The circuit of Figure 13 places an NPN transistor (2N3904 or similar) within the op-amp feedback loop to implement a digitally programmable, unidirectional current source. This circuit can be used to drive 4mA to 20mA current loops, which are commonly used in industrial-control applications. The output current is calculated with the following equation:

$$IOUT = (VREF/R) \times (NB/4096)$$

where NB is the numeric value of the DAC's binary input code and R is the sense resistor shown in Figure 13.

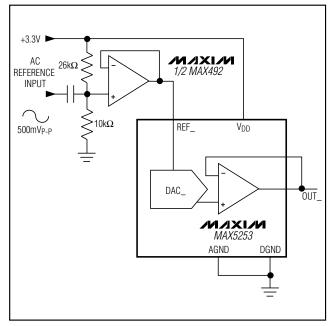


Figure 12. AC Reference Input Circuit

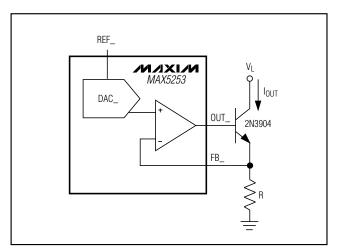


Figure 13. Digitally Programmable Current Source

Power-Supply Considerations

On power-up, all input and DAC registers are cleared (set to zero code) and DOUT is in Mode 0 (serial data is shifted out of DOUT on the clock's falling edge).

For rated MAX5253 performance, limit REFAB/REFCD to less than 1.4V below VDD. Bypass VDD with a 4.7 μ F capacitor in parallel with a 0.1 μ F capacitor to AGND. Use short lead lengths and place the bypass capacitors as close to the supply pins as possible.

Grounding and Layout Considerations

Digital or AC transient signals between AGND and DGND can create noise at the analog outputs. Tie AGND and DGND together at the DAC, then tie this point to the highest-quality ground available.

Good printed circuit board ground layout minimizes crosstalk between DAC outputs, reference inputs, and digital inputs. Reduce crosstalk by keeping analog lines away from digital lines. Wire-wrapped boards are not recommended.

TOP VIEW AGND 20 V_{DD} 19 FBD FBA OUTA 3 18 OUTD 17 OUTC OUTB 4 MIXIM MAX5253 FBB 5 16 FBC 15 REFCD REFAB 6 CL 14 PDL CS 8 13 UPO 12 DIN DOUT 11 DGND SCLK 10 DIP/SSOP

Pin Configuration

_Ordering Information (continued)

_____Chip Information

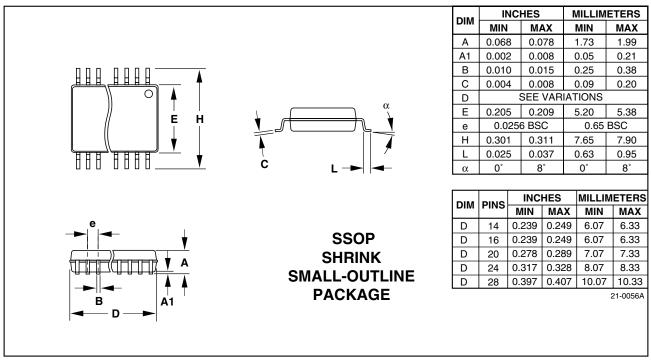
TRANSISTOR COUNT: 4337

PART	TEMP RANGE	PIN-PACKAGE	INL (LSBs)
MAX5253BC/D	0°C to +70°C	Dice*	±1
MAX5253AEPP	-40°C to +85°C	20 Plastic DIP	±1/2
MAX5253BEPP	-40°C to +85°C	20 Plastic DIP	±1
MAX5253AEAP	-40°C to +85°C	20 SSOP	±1/2
MAX5253BEAP	-40°C to +85°C	20 SSOP	±1
MAX5253BMJP	-55°C to +125°C	20 CERDIP**	±2

^{*} Dice are specified at $T_A = +25$ °C, DC parameters only.

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to **www.maxim-ic.com/packages**.)



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

16 ______Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600

© 2002 Maxim Integrated Products

Printed USA

is a registered trademark of Maxim Integrated Products.

^{**}Contact factory for availability and processing to MIL-STD-883.